



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Teck Kheng Lee

Serial No.: 10/782,270

Filed: February 18, 2004

For: INTERPOSER SUBSTRATE AND
WAFER SCALE INTERPOSER
SUBSTRATE MEMBER FOR USE WITH
FLIP-CHIP CONFIGURED
SEMICONDUCTOR DICE

Confirmation No.: 4215

Examiner: J. Clark

Group Art Unit: 2815

Attorney Docket No.: 2269-4973.1US
(00-0593.01/US)

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EL994824927US

Date of Deposit with USPS: February 22, 2005

Person making Deposit: Steven P. Wong

COMMUNICATION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

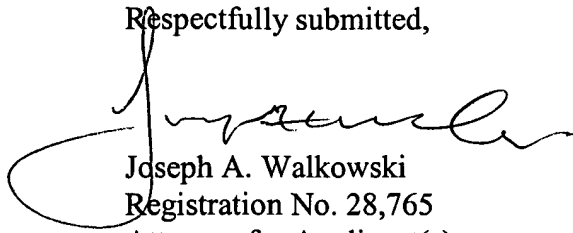
Sir:

Applicant notes the previous mailing to the Office in the present application a Supplemental Information Disclosure Statement on February 10, 2005, one day after the issuance of a Notice of Allowance and Fee(s) Due. As the Supplemental Information Disclosure Statement cited at least one document known to Applicant more than three (3) months prior to the mailing thereof to the Office, Applicant has now filed a Request for Continued Examination with a Supplemental Information Disclosure Statement identical to that mailed on February 10, 2005 for proper consideration of the documents cited therein.

Serial No. 10/782,270

Applicant respectfully requests that the documents cited in the Supplemental Information Disclosure Statement filed herewith be considered by the Examiner and made of record herein.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'Joseph A. Walkowski', is written over the typed name and registration number.

Joseph A. Walkowski
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Date: February 22, 2005
JAW/djp:ljb
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